



## Product Change Notification / LIAL-25EAAM695

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**Date:**

17-Jul-2024

**Product Category:**

Memory

**PCN Type:**

Manufacturing Change

**Notification Subject:**

CCB 5242 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material and 8008MD as a new die attach material for selected 24LCxxx, 24AAxxx and 24FCxxx device families available in 5L SOT-23 package assembled at MMT assembly site.

**Affected CPNs:**

[LIAL-25EAAM695\\_Affected\\_CPN\\_07172024.pdf](#)  
[LIAL-25EAAM695\\_Affected\\_CPN\\_07172024.csv](#)

**Notification Text:**

**PCN Status:**Final Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.  
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material and 8008MD as a new die attach material for selected 24LCxxx, 24AAxxx and 24FCxxx device families available in 5L SOT-23 package assembled at MMT assembly site.

**Pre and Post Change Summary:**

	Pre Change	Post Change
Assembly Site	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (Branch) (MMT)
Wire Material	Au	CuPdAu
Die Attach Material	8390A	8008MD
Molding Compound Material	G600V	G600V
Lead-Frame Material	CDA194	A194

Note: \* C194, A194 or CDA194 Lead frame material are the same, it is just a MCHP internal labelling difference”.

**Impacts to Data Sheet:**None

**Change Impact:**None

**Reason for Change:**To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material and 8008MD as a new die attach material.

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**August 20, 2024 (date code: 2434)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	September 2022					>	July 2024				August 2024				
	36	37	38	39	40		27	28	29	30	31	32	33	34	35
Workweek															
Initial PCN Issue Date					x										
Qual Report Availability								x							
Final PCN Issue Date									x						
Estimated Implementation													x		

Date														
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**Method to Identify Change:**Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**September 28, 2022: Issued initial notification.

July 17, 2024: Issued final notification. Updated the notification subject, description of change, qual title and purpose to reflect 8008MD as a new die attach material. Updated Pre and Post change comparison table to reflect the new die attach from 8390A to 8008MD and LF material from CDA194 to A194 based on the updated qualification data. Attached the Qualification Report. Provided estimated first ship date to be on August 20, 2024.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachments:**

[PCN\\_LIAL-25EAAM695 Qual Report.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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